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November 2015

FDBL0240N100

N-Channel PowerTrench[®] MOSFET 100 V, 210 A, 2.8 m Ω

Features

- Max $R_{DS(on)}$ = 2.8 m Ω at V_{GS} = 10 V, I_D = 80 A
- \blacksquare Max $Q_{g(tot)}$ = 111 nC at V_{GS} = 10 V, I_D = 80 A

TOP

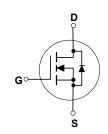
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch







MO-299A

MOSFET Maximum Ratings T_C = 25 °C unless otherwise noted.

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _C = 25°C	(Note 5)	210	
I_D	-Continuous	T _C = 100°C	(Note 5)	150	Α
	-Pulsed		(Note 4)	910	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	821	mJ
P _D	Power Dissipation	T _C = 25°C		300	W
	Power Dissipation	T _A = 25°C	(Note 1a)	3.5	v
T _J , T _{STG}	Operating and Storage Junction Temperation	ture Range		-55 to +175	°C

BOTTOM

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	43	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0240N100	FDBL0240N100	MO-299A	-	-	-

Electrical Characteristics T_J = 25 °C unless otherwise noted.

Symbol	Parameter Test Conditions		Min.	Тур.	Max.	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		58		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	2.9	4	V
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}$		2.2	2.8	mΩ
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-13		mV/°C
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, Id = 80 A		162		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 50 V V - 0 V	5835	8755	pF
Coss	Output Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	1235	1855	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	41	65	pF
R_q	Gate Resistance	V _{GS} = 0.5V, f = 1MHz	2.5		Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time				26	42	ns
t _r	Rise Time		$V_{DD} = 50 \text{ V}, I_D = 80 \text{ A},$		32	51	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{GEN}	η = 6 Ω		44	70	ns
t _f	Fall Time				17	30	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 to 10 V			79	111	nC
$Q_{g(th)}$	Threshold Gate Charge	V _{GS} = 0 to 2 V	V _{DD} = 50 V,		11	15	nC
Q_{gs}	Gate to Source Gate Charge		I _D = 80 A		27		nC
Q_{gd}	Gate to Drain "Miller" Charge				16		nC

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	210	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	910	Α
V	Veb 1500fce to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 80 \text{ A}$ (Note 2))	0.8	1.3	\/
v _{SD}		$V_{GS} = 0 \text{ V}, I_S = 40 \text{ A}$ (Note 2))	0.8	1.2	V
t _{rr}	Reverse Recovery Time	- I _E = 80 A, di/dt = 100 A/μs		82	131	ns
Q _{rr}	Reverse Recovery Charge	- 1 _F = 30 A, αι/αι = 100 A/μS		151	242	nC

Notes:

a) 43 °C/W when mounted on a 1 in² pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0 %.
- 3. E_{AS} of 821 mJ is based on starting T_J = 25 °C, L = 0.3 mH, I_{AS} = 74 A, V_{DD} = 90 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 106 A.
- ${\bf 4.\ Pulsed\ Id\ please\ refer\ to\ Figure\ "Forward\ Bias\ Safe\ Operating\ Area"\ for\ more\ details.}$
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

 R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.

Typical Characteristics $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted.

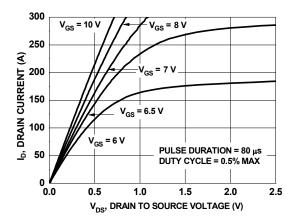


Figure 1. On Region Characteristics

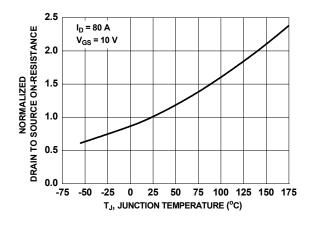


Figure 3. Normalized On Resistance vs. Junction Temperature

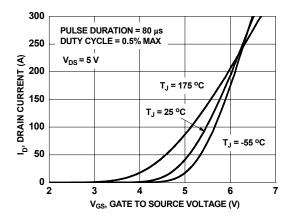


Figure 5. Transfer Characteristics

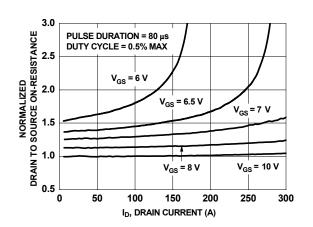


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

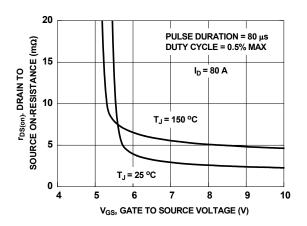


Figure 4. On-Resistance vs. Gate to Source Voltage

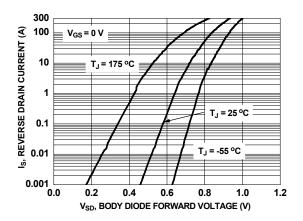


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

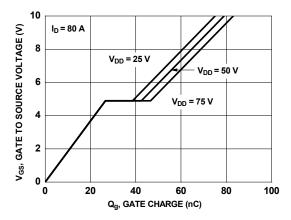


Figure 7. Gate Charge Characteristics

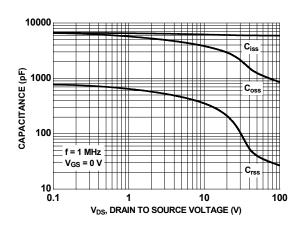


Figure 8. Capacitance vs. Drain to Source Voltage

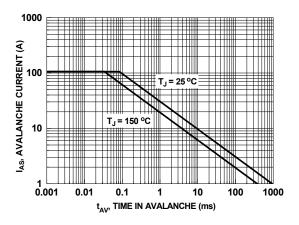


Figure 9. Unclamped Inductive Switching Capability

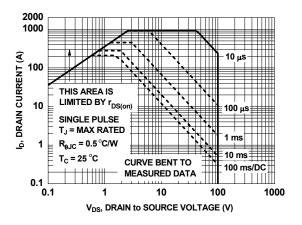


Figure 10. Forward Bias Safe Operating Area

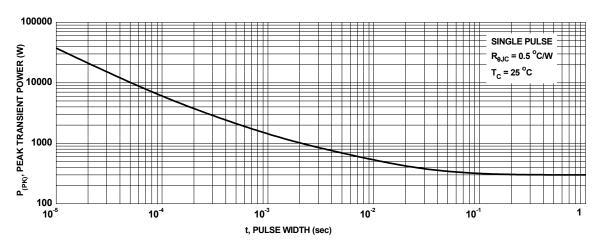


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

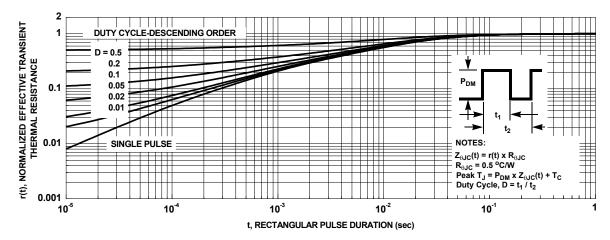
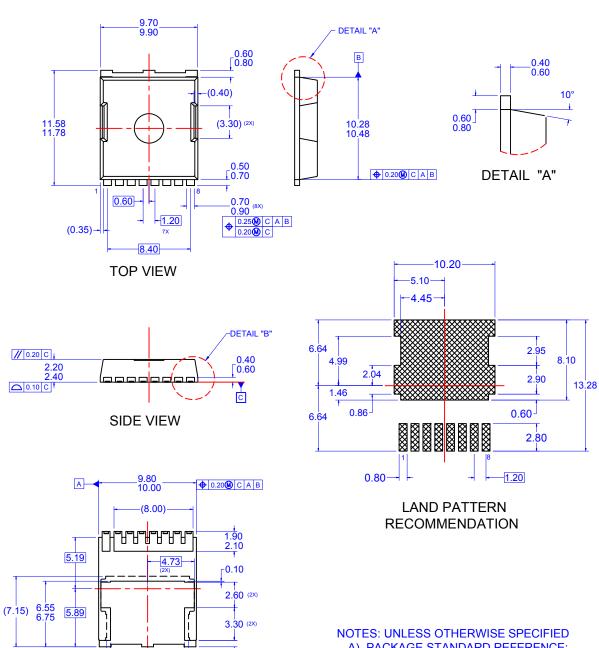


Figure 12. Junction-to-Case Transient Thermal Response Curve



- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER 2009.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

2.60 (2) 2.60 (2) 3.30 (2) 3.75 3x 0.65 2x 0.65 2x 0.65 2x 0.65 2x 0.65 0.760 0.7

10° -(0.35)

DETAIL "B"

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